XILINX

PK166 (v1.3) January 23, 2019

100% Material Declaration Data Sheet for PQ208 Package

Average Weight : 5.3000 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silver Epoxy					**0.002731**	**0.05153%**
	Silver	7440-22-4	85.3		0.002330	
	Epoxy resin	Trade Secret	5.4		0.000147	
	Organic anhydride	Trade Secret	3.1		0.000085	
	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl) phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2, 6-bis (2,3-epoxypropyl) phenoxy)-2-hydroxyp	-	3.1		0.000085	
	Anhydride	Trade Secret	3.1		0.000085	
Die					**0.021833**	**0.41194%**
	Silicon	7440-21-3	100.00		0.021833	
Copper Wire					**0.002031**	**0.03832%**
	Copper	7440-50-8	98.08		0.001992	
	Palladium	7440-05-3	1.8		0.000037	
	Gold	7440-57-5	0.12		0.000002	
Mold Compound					**4.942433**	**93.25345%**
	Epoxy Resin	Trade Secret	10		0.494243	
	Phenol Resin	Trade Secret	5		0.247122	
	Silica(Amorphous) A	60676-86-0	74		3.657400	
	Silica(Amorphous) B	7631-86-9	10		0.494243	
	Carbon Black	1333-86-4	1		0.049424	
Leadframe Tape					**0.006000**	**0.11321%**
	NBR	9003-18-3	14		0.000840	
	Phenol Resin	28453-20-5	14		0.000840	
	Bismaleimide	79922-55-7	14		0.000840	
	Polyimide Film	Trade Secret	58		0.003480	
Leadframe					**0.324972**	**6.13155%**
	Nickel Plating	7440-02-0	0.325		0.001056	
	Palladium Plating	7440-05-3	0.0175		0.000057	
	Gold Plating	7440-57-5	0.004		0.000013	
	Copper	7440-50-8	95.5535		0.310522	
	Magnesium	7439-95-4	0.175		0.000569	
	Silicon	7440-21-3	0.725		0.002356	
	Nickel	7440-02-0	3.2		0.010399	

Revision History

Date	Version	Description of Revisions
3/23/2006	1.0	Initial Xilinx release.
6/5/2006	1.1	100% Material Declaration
10/3/2006	1.2	Updated component descriptions.
10/19/2006	1.2.1	Updated component weight
1/23/2019	1.3	Updated Leadframe component, per XCN18024

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